



Material Content Data Sheet



Sales Product Name	TLE8104E			Issued	1. August 2018			
MA#	MA001036036							
Package	PG-DSO-20-71			Weight*	598.01 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.435	1.74	1.74	17449	17449
leadframe	inorganic material	phosphorus	7723-14-0	0.051	0.01		85	
	non noble metal	zinc	7440-66-6	0.203	0.03		339	
	non noble metal	iron	7439-89-6	4.058	0.68		6785	
wire	non noble metal	copper	7440-50-8	164.755	27.55	28.27	275508	282717
	non noble metal	copper	7440-50-8	1.509	0.25	0.25	2523	2523
	encapsulation	organic material	carbon black	1333-86-4	0.817	0.14		1366
encapsulation	plastics	epoxy resin	-	37.589	6.29		62857	
	inorganic material	silicondioxide	60676-86-0	370.171	61.90	68.33	619010	683233
leadfinish	non noble metal	tin	7440-31-5	4.487	0.75	0.75	7503	7503
plating	noble metal	silver	7440-22-4	0.767	0.13	0.13	1283	1283
glue	plastics	epoxy resin	-	0.791	0.13		1323	
	noble metal	silver	7440-22-4	2.373	0.40	0.53	3969	5292
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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